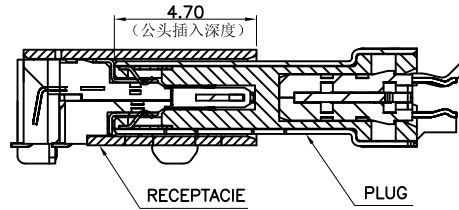
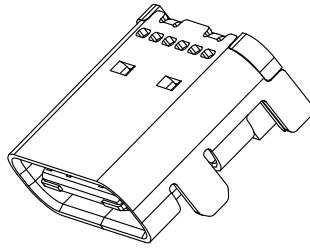
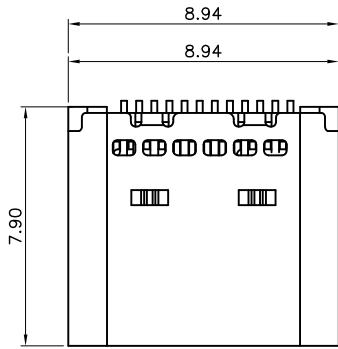
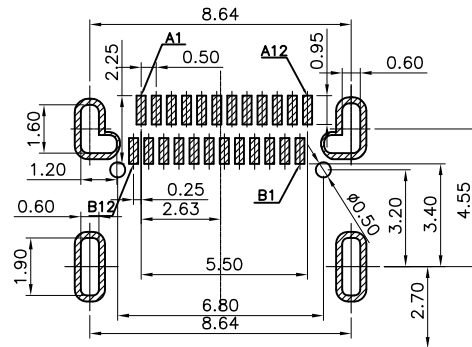
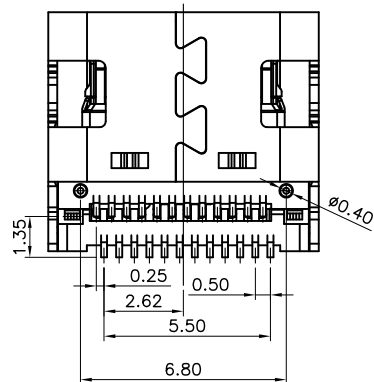
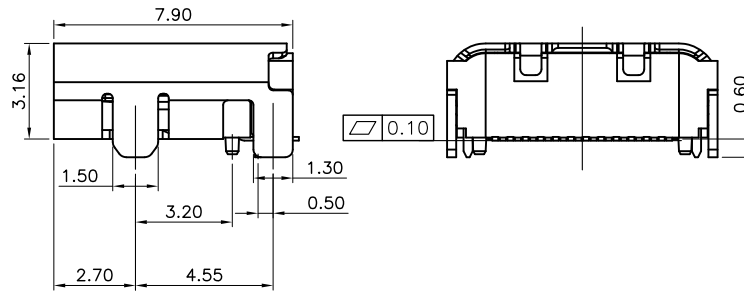
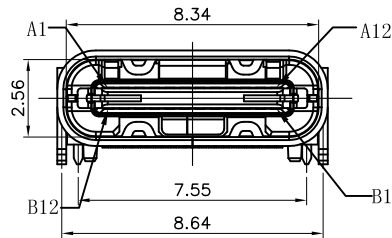


REV	ECN NO.	DISCRIPTION	CHEKED/DATE	APPD/DATE



- NOTES:
- MATERIAL:
    - MOLDING: LCP UL94 V-0
    - CONTACT: COPPER ALLOY.
    - GOLD PLATED Min ON CONTACT AREA, 100u"
    - Min TIN (LEAD FREE) ON SOLDER AREA,
    - SHELL: SUS304-H, T=0.30±0.03mm
    - 50u" NICKEL PLATING OVER ALL.
    - SHILD: SUS304-H, T=0.12±0.03mm
  - MECHANICAL:
    - INSERTION: 5~20N.
    - EXTRACTION: 8~20N AFTER TEST.
    - DURABILITY: 10000 CYCLES
  - ELECTRICAL:
    - CURRENT: 5A FOR VBUS;
    - 1.25A FOR GND PIN.
    - 0.25A FOR OTHER.
    - VOLTAGE: 20 V MAX
    - WITHSTANDING VOLTAGE: 100V AC R.M.S.
    - CONTACT RESISTANCE: 40mΩ MAX.
    - INSULATION RESISTANCE: 100MΩ MIN.
  - ENVIRONMENTAL
    - TEMPERATURE RANGE -25°C ~ +85°C



RECOMMENDED P.C.B. LAYOUT  
TOLERANCE UNSPECIFIED ±0.05mm

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

# HDC 有限公司

.X: ±0.25	.X: ±1°	APP.		DWG NO.	
.XX: ±0.15	.X: ±0.5°	CHK.		TITLE	USB 3.1 C SMT 板上双贴母座
.XXX: ±0.05	.XX: ±0.02°	DGN.	15.11.13	SERIES	005-9
UNIT	mm	DRW.	15.11.13		
SCALE	1:1				
REV.	A0	SHEET:	1/1		